



# SILICON EPITAXIAL POWER TRANSISTORS

MJE15032 NPN MJE15033 PNP



TO - 220 Leaded Plastic Package RoHS compliant

#### TO-220

## **APPLICATIONS:**

1. High - Frequency Drivers in Audio Amplifier

## **ABSOLUTE MAXIMUM RATINGS** (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT
Collector- Base Voltage	V <sub>CBO</sub>	250	V
Collector- Emitter Voltage	V <sub>CEO</sub>	250	V
Emitter- Base Voltage	V <sub>EBO</sub>	5	V
Collector Current Continuous		8	А
Collector Current Peak	- I <sub>C</sub>	16	А
Base Current	Ι <sub>Β</sub>	2	А
Power Dissipation TC=25°C	Р	50	W
Derate Above 25°C	- P <sub>D</sub>	0.4	W/ºC
Power Dissipation TA=25°C	Р	2	W
Derate Above 25°C	- P <sub>D</sub>	0.016	W/ºC
Operating & Storage Junction Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-65 to +150	°C

## **Thermal Resistance**

Thermal Ambient	R <sub>th (j-a)</sub>	62.5	°C/W
Junction to Case	R <sub>th (j-c)</sub>	2.5	°C/W





## **ELECTRICAL CHARACTERISTICS at** (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Collector- Emitter Suntanning Voltage	$V_{\text{CEO(sus)}}^{1}$	I <sub>C</sub> =10mA, I <sub>B</sub> =0	250			V
Collector Cut Off Current	I <sub>CBO</sub>	V <sub>CB</sub> =150V, I <sub>E</sub> =0	-		10	μA
Emitter Cut Off Current	I <sub>EBO</sub>	V <sub>BE</sub> =5V, I <sub>C</sub> =0	1		10	μA
		I <sub>C</sub> =0.5A, V <sub>CE</sub> =5V	50			
DC Current Gain	h <sub>FE</sub> <sup>1</sup>	I <sub>C</sub> =1.0A, V <sub>CE</sub> =5V	50			
		I <sub>C</sub> =2A, V <sub>CE</sub> =5V	10			
Collector Emitter Saturation Voltage	V <sub>CE(sat)</sub> <sup>1</sup>	<sub>IC</sub> =1A, I <sub>B</sub> =0.1A			0.5	V
Base Emitter on Voltage	V <sub>BE(on)</sub> <sup>1</sup>	I <sub>C</sub> =1.0A, V <sub>CE</sub> =5V			1.0	V
Dynamic Characteristics						
Current Gain - Bandwidth Product	f <sub>T</sub> <sup>2</sup>	I <sub>C</sub> =500mA, V <sub>CE</sub> =10V ftest=1MHz	30			MHz

Note:

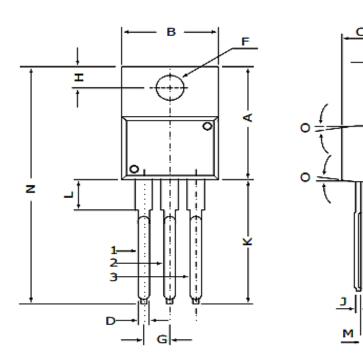
1. Pulse Test: Pulse Width  $\leq$  300ms, Duty Cycle  $\leq$ 2 %

2.  $f_T$ = Ihfel. ftest.

3. For PNP devices voltage and current values will be negative (-)



# PACKAGE DETAILS



TO-220 Plastic Package

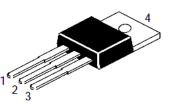
F

DIM	MIN	MAX		
Α	14.42	16.51		
В	9.63	10.67		
С	3.56	4.83		
D		0.90		
E	1.15	1.40		
F	3.75	3.88		
G	2.29	2.79		
Н	2.54	3.43		
J	- 0.56			
K	12.70	14.73		
L	2.80	4.07		
M	2.03	2.92		
N	_	31.24		
0	7 DEG			
All diminsions in mm.				

ALL DIMENSIONS IN MM

## PIN CONFIGURATION

- 1. BASE
- 2. COLLECTOR
- 3. EMITTER
- 4. COLLECTOR

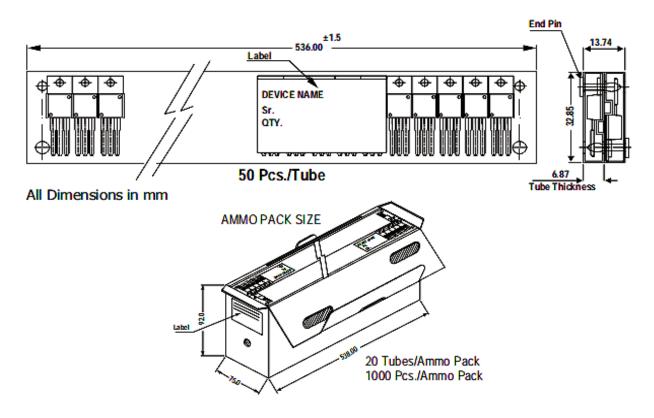


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# TO-220 Tube Packing



## **Packing Detail**

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	GrWt
TO-220		396 gm/200 pcs 135 gm/50 pcs	3" x 7.5" x 7.5" 3.5" x 3.7" x 21.5"		17" x 15" x 13.5" 19" x 19" x 19"	16K 10K	36 kgs 28 kgs



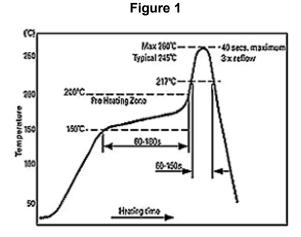


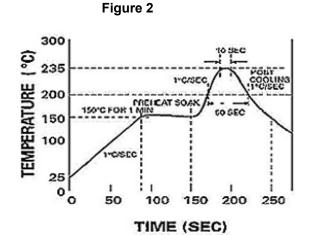
#### **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.





Reflow profiles in tabular form **Sn-Pb System Pb-Free System Profile Feature** Average Ramp-Up Rate ~3°C/second ~3°C/second Preheat Temperature Range 150-170°C 150-200°C 60-180 seconds – Time 60-180 seconds Time maintained above: - Temperature 200°C 217°C – Time 60-150 seconds 30-50 seconds Peak Temperature 235°C 260°C max. Time within +0 -5°C of actual Peak 10 seconds 40 seconds Ramp-Down Rate 3°C/second max. 6°C/second max.

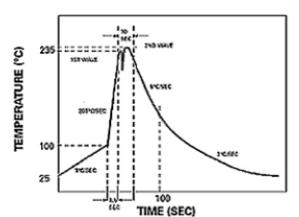




## **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

C) 210 ISTANYE 30°CSBC 30°CSBC 30°CSBC 100 100 100 100 TIME (SEC)



The Recommended solder Profile For Devices

with Pb-free terminal plating used with leaded

solder, or for devices with leaded terminal

plating used with leaded solder

#### Wave Profiles in Tabular Form

Wave Fromes in Fabrial Form					
Profile Feature	Sn-Pb System	Pb-Free System			
Average Ramp-Up Rate	~200°C/second	~200°C/second			
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec			
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp			
Peak Temperature	235°C	260°C max.			
Time within +0 -5°C of actual Peak	10 seconds	10 seconds			
Ramp-Down Rate	5°C/second max.	5°C/second max			

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## Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- $\cdot$  Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- $\cdot$  Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- $\cdot\,$  The product shall be stored on a plane area. They should not be turned upside down.
- They should not be placed against the wall.

#### Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

#### Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start. For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		





## **Customer Notes**

#### **Component Disposal Instructions**

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

## Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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